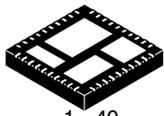


# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

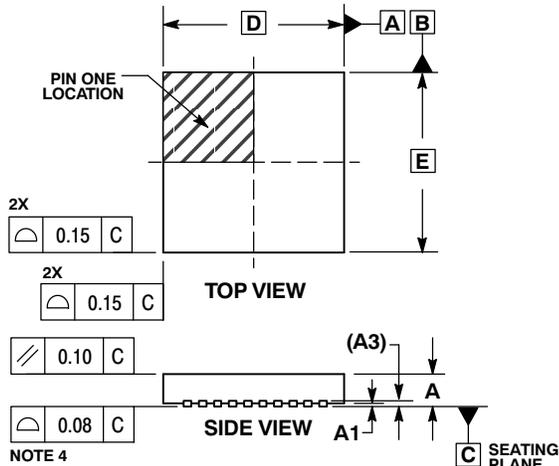
ON Semiconductor®



1 40  
SCALE 2:1

QFN40 6x6, 0.5P  
CASE 485AK-01  
ISSUE A

DATE 26 OCT 2007

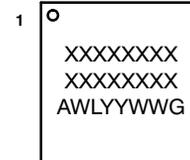


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSIONS: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM TERMINAL
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

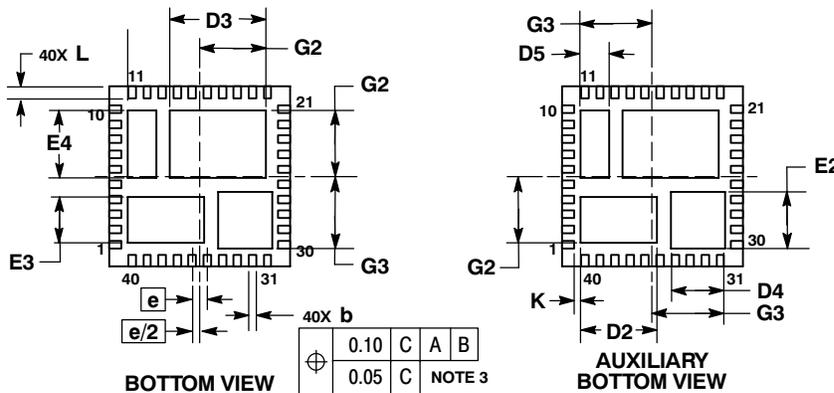
DIM	MILLIMETERS	
	MIN	MAX
A	0.80	1.00
A1	---	0.05
A3	0.20	REF
b	0.18	0.30
D	6.00	BSC
D2	2.45	2.65
D3	3.10	3.30
D4	1.70	1.90
D5	0.85	1.05
E	6.00	BSC
E2	1.80	2.00
E3	1.43	1.63
E4	2.15	2.35
e	0.50	BSC
G2	2.10	2.30
G3	2.30	2.50
K	0.20	---
L	0.30	0.50

### GENERIC MARKING DIAGRAM\*

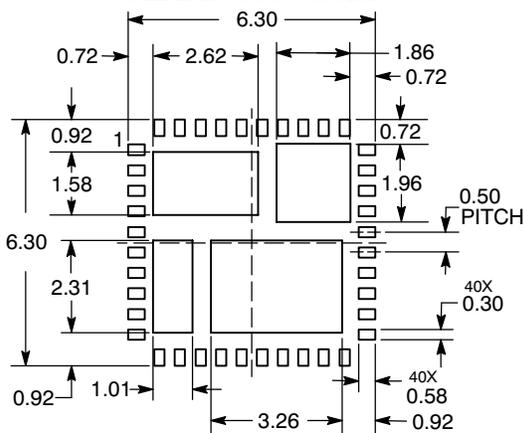


- XXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.



### SOLDERING FOOTPRINT



DIMENSIONS: MILLIMETERS

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<b>STATUS:</b>	ON SEMICONDUCTOR STANDARD	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	QFN40 6x6, 0.5P	<b>PAGE 1 OF 2</b>

